Octal Buffer/Line Driver with 3-State Outputs

74AC240, 74ACT240

General Description

The AC240/ACT240 is an octal buffer and line driver designed to be employed as memory and address driver, clock drivers and bus oriented transmitter or receiver which provides improved PC board density.

Features

- I_{CC} and I_{OZ} Reduced by 50%
- Inverting 3−State Outputs drive Bus Lines or Buffer Memory Address Registers
- Outputs Source/Sink 24 mA
- ACT240 has TTL−compatible Inputs
- These are Pb−Free Devices

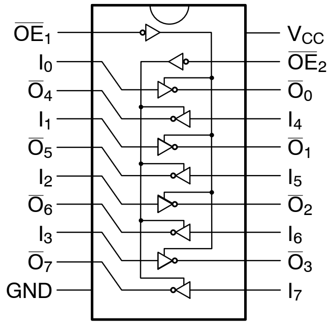


Figure 1. Connection Diagram

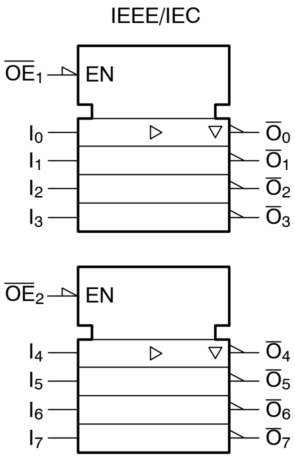


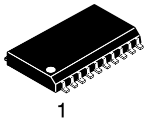
Figure 2. Logic Symbol

TRUTH TABLES

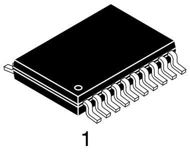
Inputs		Outputs
$\overline{OE}_1$	I_n	(Pins 12, 14, 16, 18)
L	L	H
L	H	L
H	X	Z

Inputs		Outputs
$\overline{OE}_2$	I_n	(Pins 3, 5, 7, 9)
L	L	H
L	H	L
H	X	Z

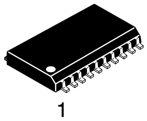
NOTE: H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance



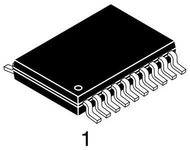
SOIC−20W
CASE 751D



TSSOP−20
CASE 948E



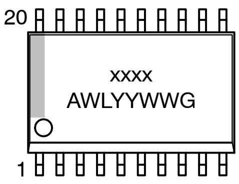
SOIC−20W
CASE 751BJ



TSSOP−20
CASE 948AQ

MARKING DIAGRAMS

SOIC−20W



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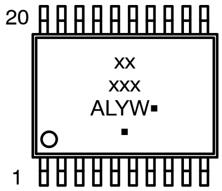


xxxx = Specific Device Code
A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or ▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

PIN DESCRIPTION

Pin Names	Description
$\overline{OE}_1$, $\overline{OE}_2$	3−State Output Enable Inputs
I_0–I_7	Inputs
$\overline{O}_0$–$\overline{O}_7$	Outputs

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Rating	Unit
V_{CC}	Supply Voltage	−0.5 to +7.0	V
I_{IK}	DC Input Diode Current $V_I = -0.5$ V $V_I = V_{CC} + 0.5$ V	 −20 +20	mA
V_I	DC Input Voltage	−0.5 to V_{CC} + 0.5	V
I_{OK}	DC Output Diode Current $V_O = -0.5$ V $V_O = V_{CC} + 0.5$ V	 −20 +20	mA
V_O	DC Output Voltage	−0.5 to V_{CC} + 0.5	V
I_O	DC Output Source or Sink Current	±50	mA
I_{CC} or I_{GND}	DC V_{CC} or Ground Current per Output Pin	±50	mA
T_{STG}	Storage Temperature	−65 to +150	°C
T_J	Junction Temperature	140	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	Supply Voltage AC ACT	 2.0 4.5	 6.0 5.5	V
V_I	Input Voltage	0	V_{CC}	V
V_O	Output Voltage	0	V_{CC}	V
T_A	Operating Temperature	−40	85	°C
$\Delta V/\Delta t$	Minimum Input Edge Rate, AC Devices: V_{IN} from 30% to 70% V_{CC}, V_{CC} @ 3.3 V, 4.5 V, 5.5 V	125		mV/ns
$\Delta V/\Delta t$	Minimum Input Edge Rate, ACT Devices: V_{IN} from 0.8 V to 2.0 V, V_{CC} @ 4.5 V, 5.5 V	125		mV/ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS FOR AC

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C		T_A = –40°C to +85°C	Units
				Typ.	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage	3.0	V_{OUT} = 0.1 V or V_{CC} – 0.1 V	1.5	2.1	2.1	V
		4.5		2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V_{IL}	Maximum LOW Level Input Voltage	3.0	V_{OUT} = 0.1 V or V_{CC} – 0.1 V	1.5	0.9	0.9	V
		4.5		2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V_{OH}	Minimum HIGH Level Output Voltage	3.0	I_{OUT} = –50 μA	2.99	2.9	2.9	V
		4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	V_{IN} = V_{IL} or V_{IH}, I_{OH} = –12 mA		2.56	2.46	
		4.5	V_{IN} = V_{IL} or V_{IH}, I_{OH} = –24 mA		3.86	3.76	
		5.5	V_{IN} = V_{IL} or V_{IH}, I_{OH} = –24 mA (1)		4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	3.0	I_{OUT} = 50 μA	0.002	0.1	0.1	V
		4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	V_{IN} = V_{IL} or V_{IH}, I_{OL} = 12 mA		0.36	0.44	
		4.5	V_{IN} = V_{IL} or V_{IH}, I_{OL} = 24 mA		0.36	0.44	
		5.5	V_{IN} = V_{IL} or V_{IH}, I_{OL} = 24 mA (1)		0.36	0.44	
I_{IN} (Note 2)	Maximum Input Leakage Current	5.5	V_I = V_{CC}, GND		±0.1	±1.0	μA
I_{OZ}	Maximum 3–STATE Leakage Current	5.5	V_I (OE) = V_{IL}, V_{IH}; V_I = V_{CC}, GND; V_O = V_{CC}, GND		±0.25	±2.5	μA
I_{OLD}	Minimum Dynamic Output Current (Note 3)	5.5	V_{OLD} = 1.65 V Max.			75	mA
I_{OHD}		5.5	V_{OHD} = 3.85 V Min.			–75	mA
I_{CC} (Note 2)	Maximum Quiescent Supply Current	5.5	V_{IN} = V_{CC} or GND		4.0	40.0	μA

1. All outputs loaded; thresholds on input associated with output under test.
2. I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.
3. Maximum test duration 2.0 ms, one output loaded at a time.

DC ELECTRICAL CHARACTERISTICS FOR ACT

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = +25°C		T_A = −40°C to +85°C	Units
				Typ.	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage	4.5	$V_{OUT} = 0.1$ V or $V_{CC} - 0.1$ V	1.5	2.0	2.0	V
		5.5		1.5	2.0	2.0	
V_{IL}	Maximum LOW Level Input Voltage	4.5	$V_{OUT} = 0.1$ V or $V_{CC} - 0.1$ V	1.5	0.8	0.8	V
		5.5		1.5	0.8	0.8	
V_{OH}	Minimum HIGH Level Output Voltage	4.5	$I_{OUT} = -50$ µA	4.49	4.4	4.4	V
		5.5		5.49	5.4	5.4	
		4.5	$V_{IN} = V_{IL}$ or V_{IH}, $I_{OH} = -24$ mA		3.86	3.76	
		5.5	$V_{IN} = V_{IL}$ or V_{IH}, $I_{OH} = -24$ mA (4)		4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	4.5	$I_{OUT} = 50$ µA	0.001	0.1	0.1	V
		5.5		0.001	0.1	0.1	
		4.5	$V_{IN} = V_{IL}$ or V_{IH}, $I_{OL} = 24$ mA		0.36	0.44	
		5.5	$V_{IN} = V_{IL}$ or V_{IH}, $I_{OL} = 24$ mA (4)		0.36	0.44	
I_{IN}	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	µA
I_{OZ}	Maximum 3−STATE Leakage Current	5.5	$V_I = V_{IL}$, V_{IH}; $V_O = V_{CC}$, GND		±0.25	±2.5	µA
I_{CCT}	Maximum I_{CC}/Input	5.5	$V_I = V_{CC} - 2.1$ V	0.6		1.5	mA
I_{OLD}	Minimum Dynamic Output Current (Note 5)	5.5	$V_{OLD} = 1.65$ V Max.			75	mA
I_{OHD}		5.5	$V_{OHD} = 3.85$ V Min.			−75	mA
I_{CC}	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	µA

4. All outputs loaded; thresholds on input associated with output under test.
5. Maximum test duration 2.0 ms, one output loaded at a time.

AC ELECTRICAL CHARACTERISTICS FOR AC

Symbol	Parameter	V_{CC} (V) (Note 6)	T_A = +25°C, C_L = 50 pF			T_A = −40°C to +85°C, C_L = 50 pF		Units
			Min.	Typ.	Max.	Min.	Max.	
t_{PLH}	Propagation Delay, Data to Output	3.3	1.5	6.0	8.0	1.0	9.0	ns
		5.0	1.5	4.5	6.5	1.0	7.0	
t_{PHL}	Propagation Delay, Data to Output	3.3	1.5	5.5	8.0	1.0	8.5	ns
		5.0	1.5	4.5	6.0	1.0	6.5	
t_{PZH}	Output Enable Time	3.3	1.5	6.0	10.5	1.0	11.0	ns
		5.0	1.5	5.0	7.0	1.0	8.0	
t_{PZL}	Output Enable Time	3.3	1.5	7.0	10.0	1.0	11.0	ns
		5.0	1.5	5.5	8.0	1.0	8.5	
t_{PHZ}	Output Disable Time	3.3	1.5	7.0	10.0	1.0	10.5	ns
		5.0	1.5	6.5	9.0	1.0	9.5	
t_{PLZ}	Output Disable Time	3.3	1.5	7.5	10.5	1.0	11.5	ns
		5.0	1.5	6.5	9.0	1.0	9.5	

6. Voltage range 3.3 is 3.3 V ± 0.3 V. Voltage range 5.0 is 5.0 V ± 0.5 V.

AC ELECTRICAL CHARACTERISTICS FOR ACT

Symbol	Parameter	V_{CC} (V) (Note 7)	T_A = +25°C, C_L = 50 pF			T_A = −40°C to +85°C, C_L = 50 pF		Units
			Min.	Typ.	Max.	Min.	Max.	
t_{PLH}	Propagation Delay, Data to Output	5.0	1.5	6.0	8.5	1.5	9.5	ns
t_{PHL}	Propagation Delay, Data to Output	5.0	1.5	5.5	7.5	1.5	8.5	ns
t_{PZH}	Output Enable Time	5.0	1.5	7.0	8.5	1.0	9.5	ns
t_{PZL}	Output Enable Time	5.0	2.0	7.0	9.5	1.5	10.5	ns
t_{PHZ}	Output Disable Time	5.0	2.0	8.0	9.5	2.0	10.5	ns
t_{PLZ}	Output Disable Time	5.0	2.5	6.5	10.0	2.0	10.5	ns

7. Voltage range 5.0 is 5.0 V ± 0.5 V.

CAPACITANCE

Symbol	Parameter	Conditions	Typ.	Units
C_{IN}	Input Capacitance	V_{CC} = OPEN	4.5	pF
C_{PD}	Power Dissipation Capacitance	V_{CC} = 5.0 V	45.0	pF

ORDERING INFORMATION

Device	Device Marking	Package	Shipping†
74AC240SCX	AC240	SOIC−20W, case 751BJ (Pb−Free)	1000 Units / Tape & Reel
74ACT240SCX	ACT240	SOIC−20W, case 751BJ (Pb−Free)	1000 Units / Tape & Reel
74ACT240MTC	ACT 240	TSSOP−20, case 948E (Pb−Free)	75 Units / Tube
74ACT240MTCX	ACT 240	TSSOP−20, case 948AQ (Pb−Free)	2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

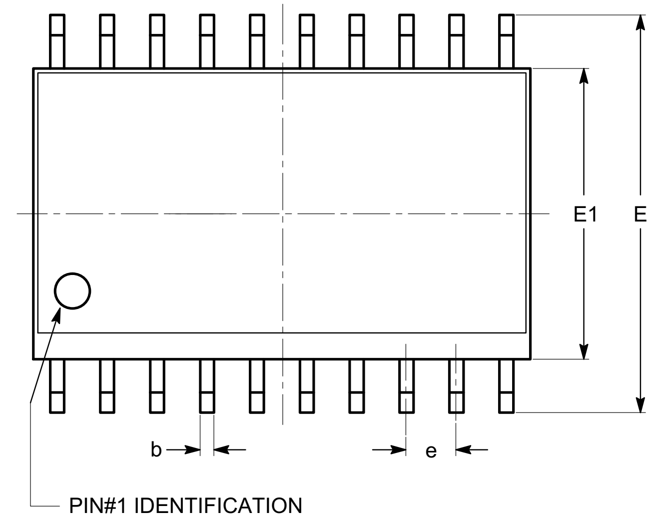
NOTE: All packages are lead free per JEDEC: J−STD−020B standard.

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

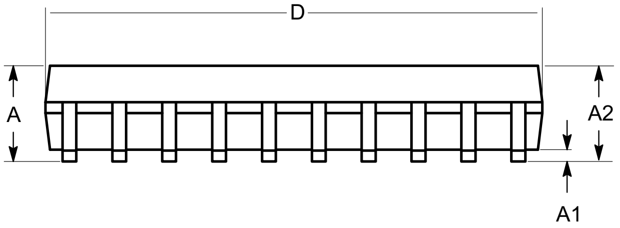
SOIC−20, 300 mils
CASE 751BJ−01
ISSUE O

DATE 19 DEC 2008

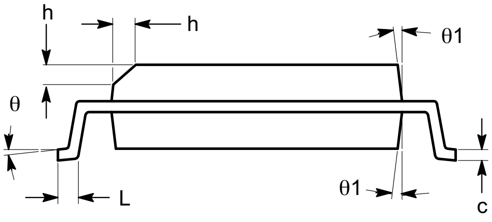


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	2.36	2.49	2.64
A1	0.10		0.30
A2	2.05		2.55
b	0.31	0.41	0.51
c	0.20	0.27	0.33
D	12.60	12.80	13.00
E	10.01	10.30	10.64
E1	7.40	7.50	7.60
e	1.27 BSC		
h	0.25		0.75
L	0.40	0.81	1.27
θ	0º		8º
θ1	5º		15º



SIDE VIEW

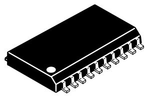


END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MS-013.

DOCUMENT NUMBER:	**98AON34287E**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	**SOIC−20, 300 MILS**	**PAGE 1 OF 1**

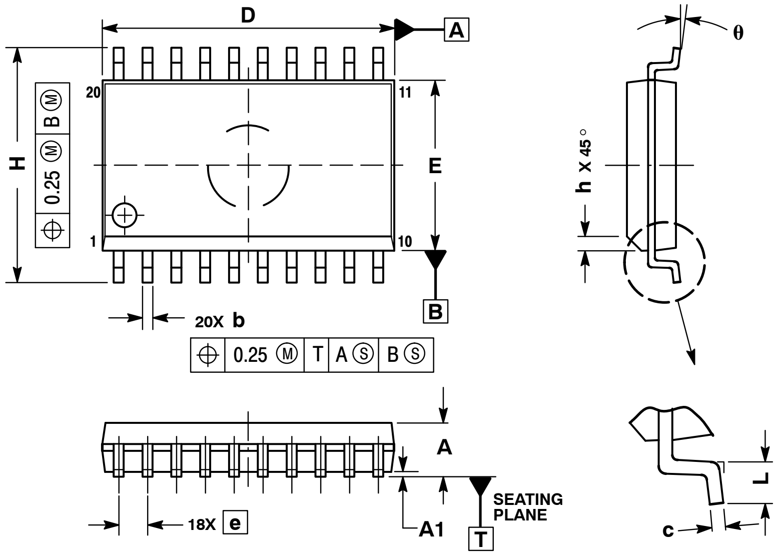
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SCALE 1:1

SOIC−20 WB
CASE 751D−05
ISSUE H

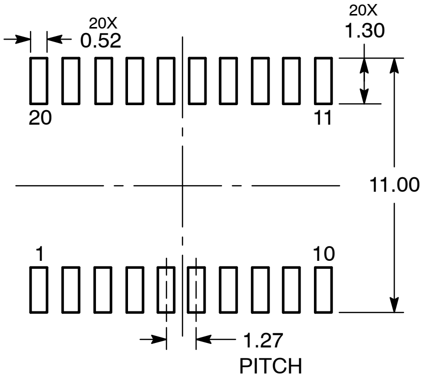
DATE 22 APR 2015



NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
b	0.35	0.49
c	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0 °	7 °

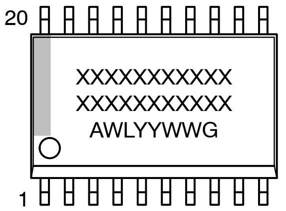
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

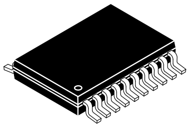
GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

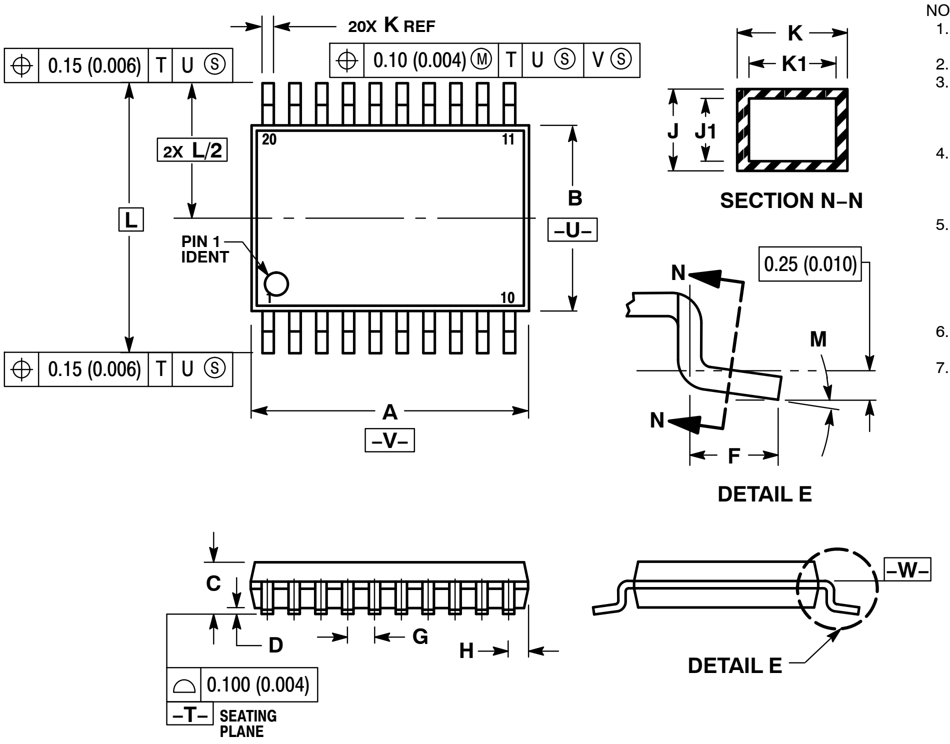
DOCUMENT NUMBER:	**98ASB42343B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**SOIC−20 WB**	**PAGE 1 OF 1**



SCALE 2:1

TSSOP−20 WB
CASE 948E
ISSUE D

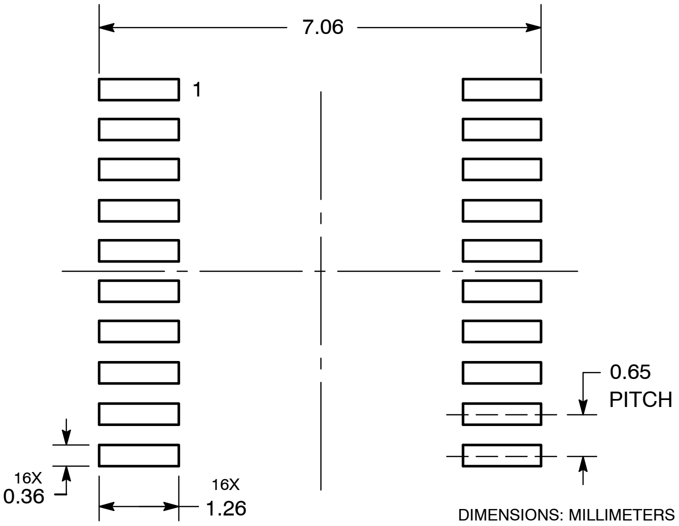
DATE 17 FEB 2016



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

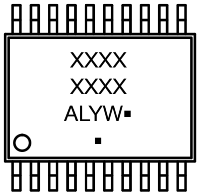
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

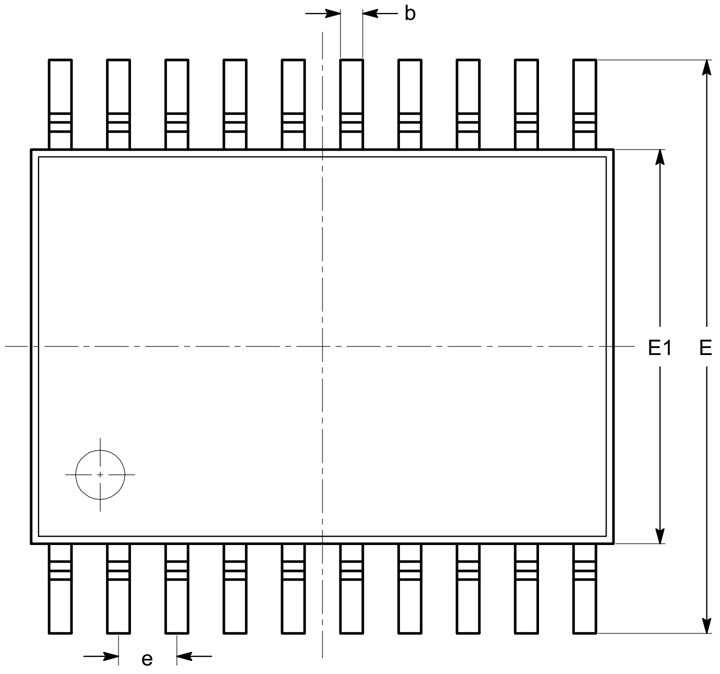
DOCUMENT NUMBER:	98ASH70169A	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	TSSOP−20 WB	PAGE 1 OF 1

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

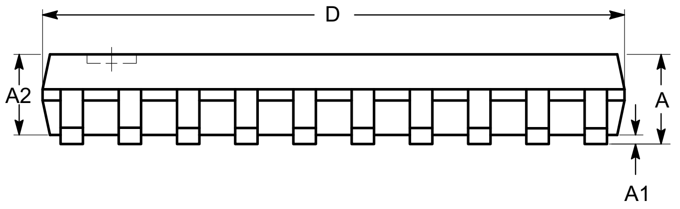
TSSOP20, 4.4x6.5
CASE 948AQ−01
ISSUE A

DATE 19 MAR 2009

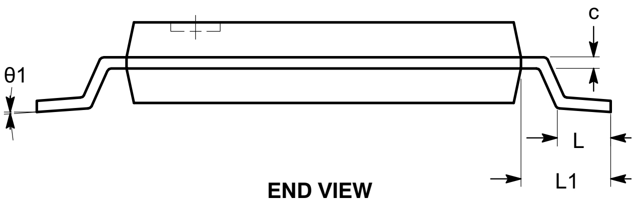


TOP VIEW

SYMBOL	MIN	NOM	MAX
A			1.20
A1	0.05		0.15
A2	0.80		1.05
b	0.19		0.30
c	0.09		0.20
D	6.40	6.50	6.60
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
e	0.65 BSC		
L	0.45	0.60	0.75
L1	1.00 REF		
θ	0º		8º



SIDE VIEW



END VIEW

Notes:

(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MO-153.

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DESCRIPTION:	**TSSOP20, 4.4X6.5**	**PAGE 1 OF 1**

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